

TO0555 ٤

Schottky Diode in a TO-252 Plastic Package.

$$H_1 \cup H_2 \overset{\gamma}{\rightarrow} \mathbb{Z} \oplus \mathbb{Z} \rightarrow Y$$

Low forward voltage drop, low power losses, High efficiency operation, High cost performance.

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LV10100DCT

Rev.F May.-2016

Parameter	N Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_{RM}	100	V
RMS Voltage	V_{RMS}	70	V
Average Rectified Forward Current	$I_{F(AV)}$	2X5	A
Non Repetitive Peak Surge Current	I_{FSM}	80	A
Typical Thermal Resistance Junction to Case	R_{JC}	2.8	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40° 150	

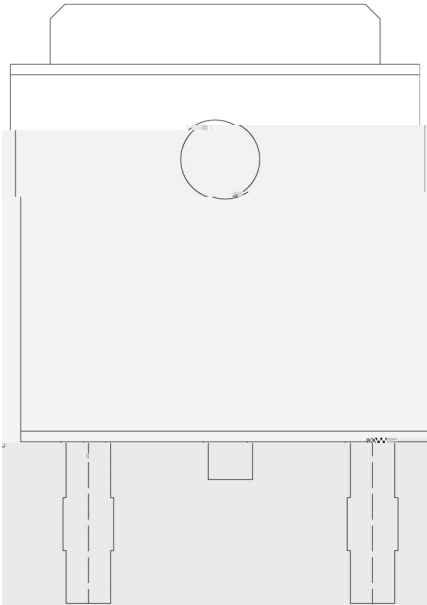
Parameter	N Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_{BR}	$I_R=1mA$ $T_a=25^\circ C$	100			V
		$I_F=3A$ $T_a=25^\circ C$		0.59		V

Forward Voltage

V_F

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/ Marking Instructions



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LV43433

FT:

Note:

BR:

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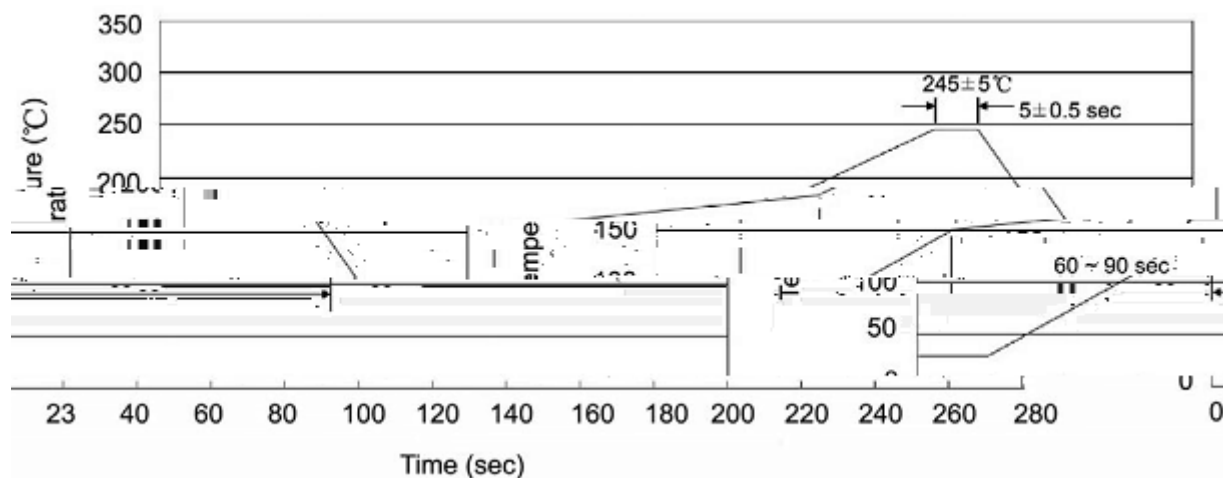
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Company Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)


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1. Preheating: 25~150 , Time: 60~90sec;
2. Peak Temp.: 245±5 , Duration: 5±0.5sec;
3. Cooling Speed: 2~10 /sec.

Note:

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2. Peak Temp.: 245±5 , Duration: 5±0.5sec.
3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5

Time: 10±1 sec.

Temp.: 260±5

Time: 10±1 sec

/ Packaging SPEC.

E / REEL

Package Type 封装	Units 包 数量				Dimension 包 尺寸 (unit: mm ³)			
	卷	卷	卷	卷	卷	卷	卷	卷

E / TUBE

Package Type 封装	Units 包 数量				Dimension 包 尺寸 (unit: mm ³)			
	卷	卷	卷	卷	卷	卷	卷	卷

/ Notices